

## TecHorizon | InfoTalk@Webinar - 19 January 2021

## **Protecting Innovation Through Patents**

New Patent System 

Patent Funding 
Patent Filing, Strategy & Analytics

A patent system seeks to protect inventions in order to encourage innovation. After years of efforts, the Government launched a new patent system in December 2019. One of the major features of the new patent system is the introduction of an original grant patent (OGP) system which provides a direct filing route for seeking standard patent protection in Hong Kong.

On 19 Jan 2021, a comprehensive webinar will be organised by Hong Kong Science & Technology Parks Corporation (HKSTP) and TecONE, and co-organised by Intellectual Property Department and Hong Kong Productivity Council. The following topics will be covered in this webinar:

- The Original Grant Patent (OGP) System in Hong Kong Highlight the key features of the new patent system and the new examination procedures.
- Patent Application Grant

A funding scheme to assist local companies and individuals to apply for patents of their own inventions. Funding amount: not more than HK\$250,000 or 90% of the sum of the total direct cost of the patent application(s).

- Patent Filing and Strategy for BioMedical Companies Explore the boundaries of what can be patented in the world of medical devices, diagnostics, therapeutics, AI for biomedical companies. Give advice on how to develop a smart, strong, and business-savvy IP strategy.
- Patent Analytics: An Innovation Landscape of AI Medical Device Get insight from the analytics of patent search results on technology development

Date:	19 January 2021 (Tuesday)
Time:	10:00 am - 12:15 pm
Language:	English
How to join:	Zoom Webinar URL will be sent to the registrants by email
	before the event day



Enquiries

For enquiries, please call +852 2780 6938 or email to tecone@hkstp.org.

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